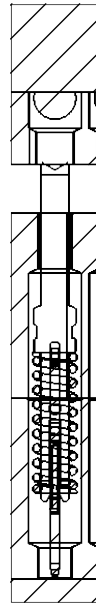
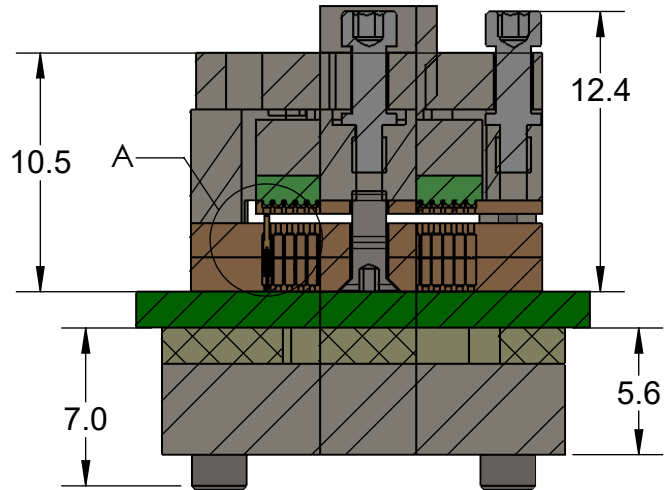
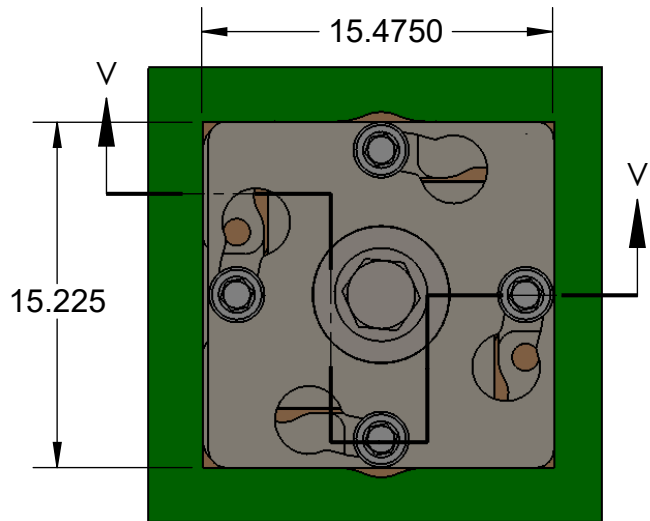
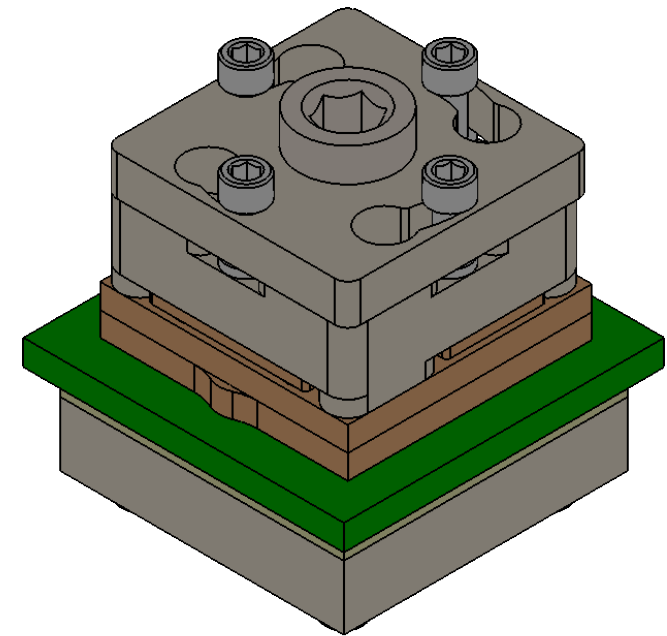


SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS



DETAIL A
SCALE 16 : 1



Features:

- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time

Description: SBT-BGA 19x19 10mmx10mm 0.5mm pitch

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-7004 Specification



Ironwood Electronics, Inc.
Tele: (800) 404-0204
www.ironwoodelectronics.com

Material: Material <not specified>
Finish:
Weight: 10.88

STATUS: Released

DRAWN BY: B. Schatz

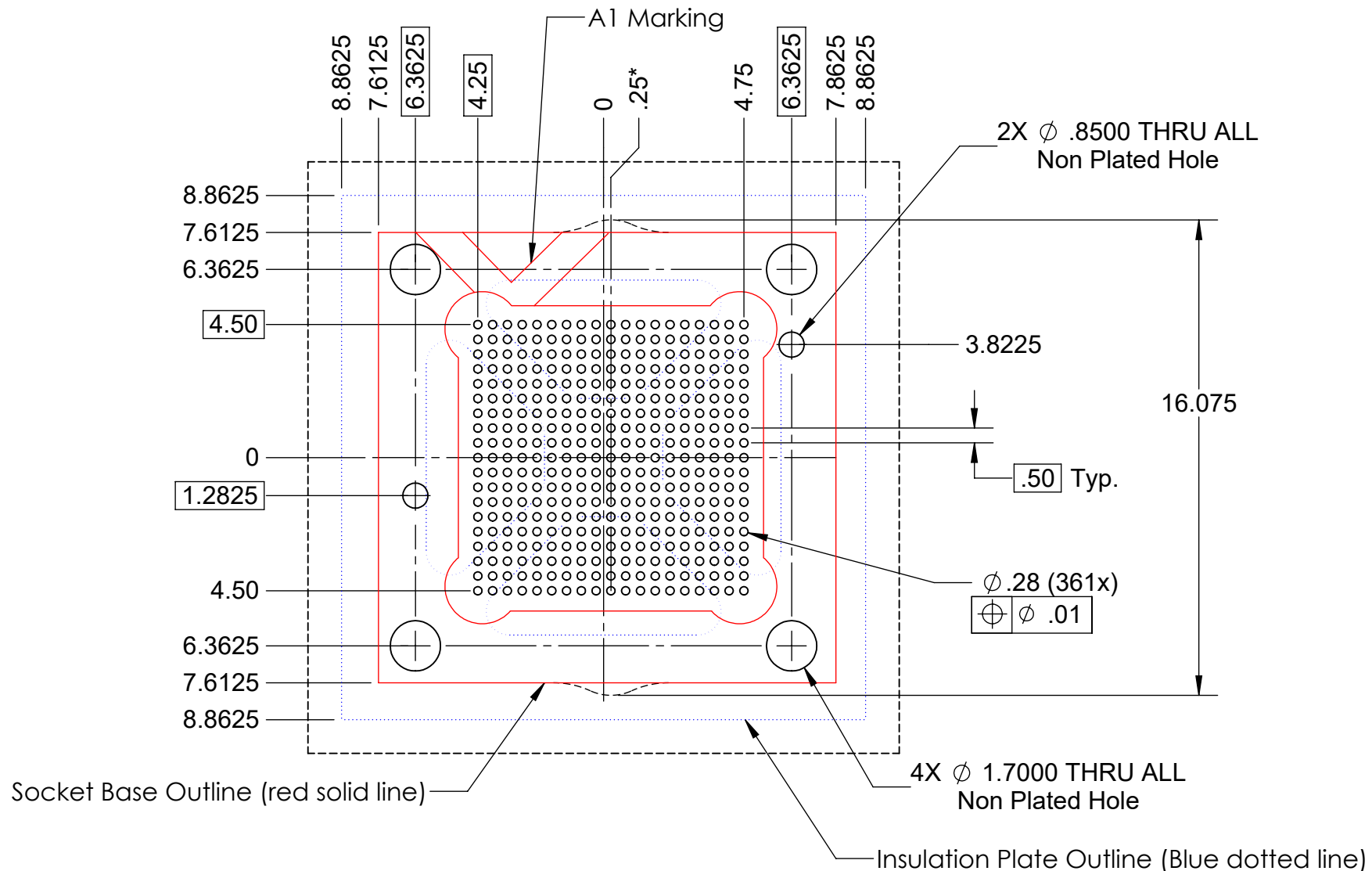
FILE: SBT-BGA-7004

SHEET: 1 OF 4

SCALE: 3:1

DATE: 8/16/2013

REV. A



NOTES:


1. Target PCB Recommendations
2. Total thickness: 1.6mm min.
3. Plating: Gold or Solder finish
4. PCB Pad height: Same or higher than solder mask

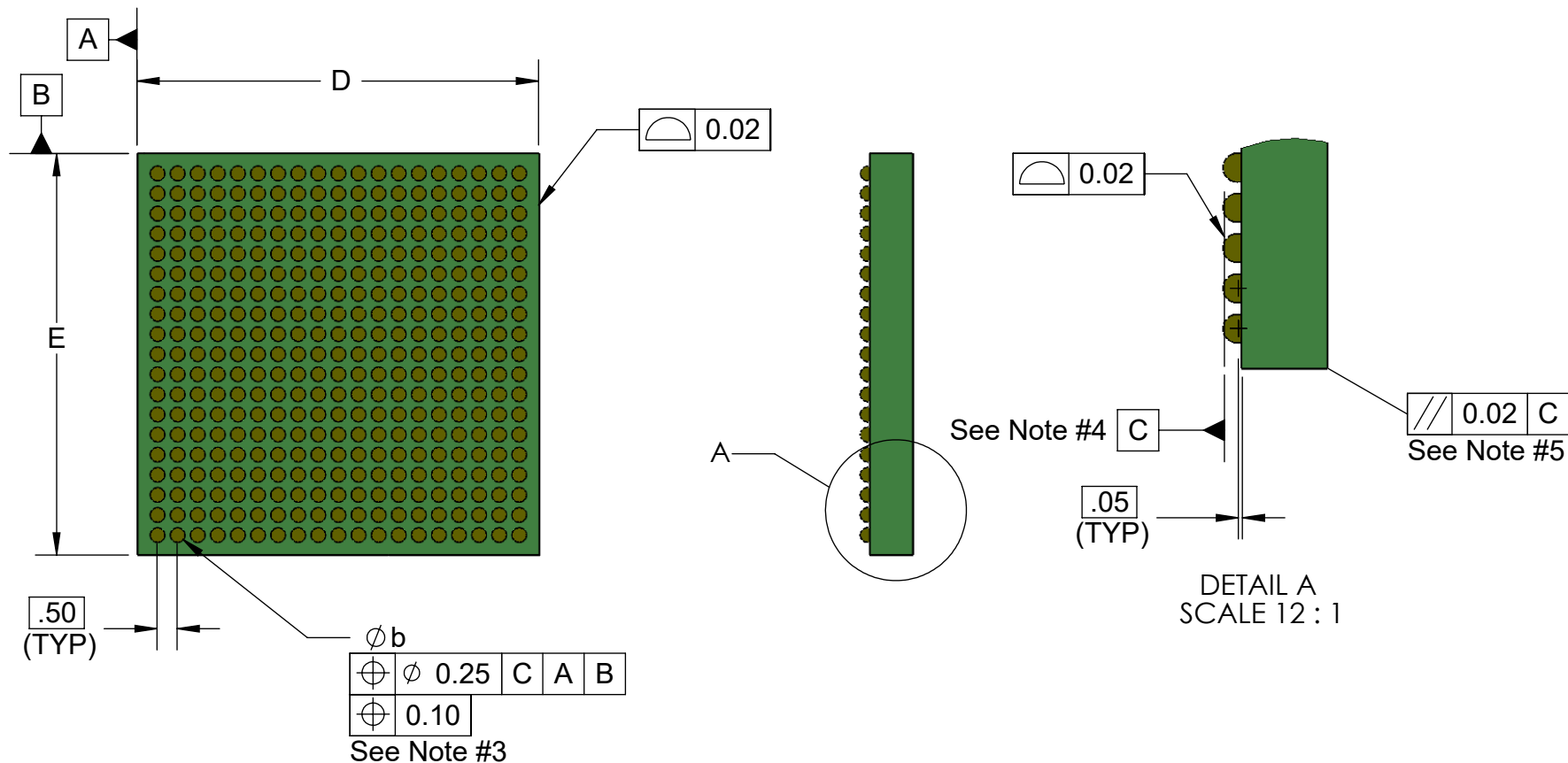
***BGA pattern is offset 0.25mm with respect to the mounting holes. 0**

Description: Recommended Layout

Primary dimension units are millimeters, Secondary dimension units are [inches]. Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: Material <not specified> Finish: Weight: 10.88</p>	STATUS: Released	SHEET: 2 OF 4	REV. A
		DRAWN BY: B. Schatz	SCALE: 5:1	
		FILE: SBT-BGA-7004	DATE: 8/16/2013	



NOTES:


1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

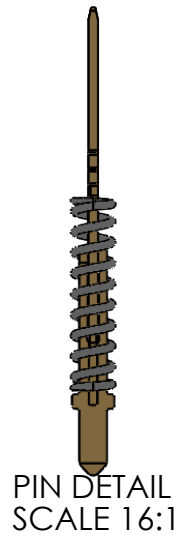
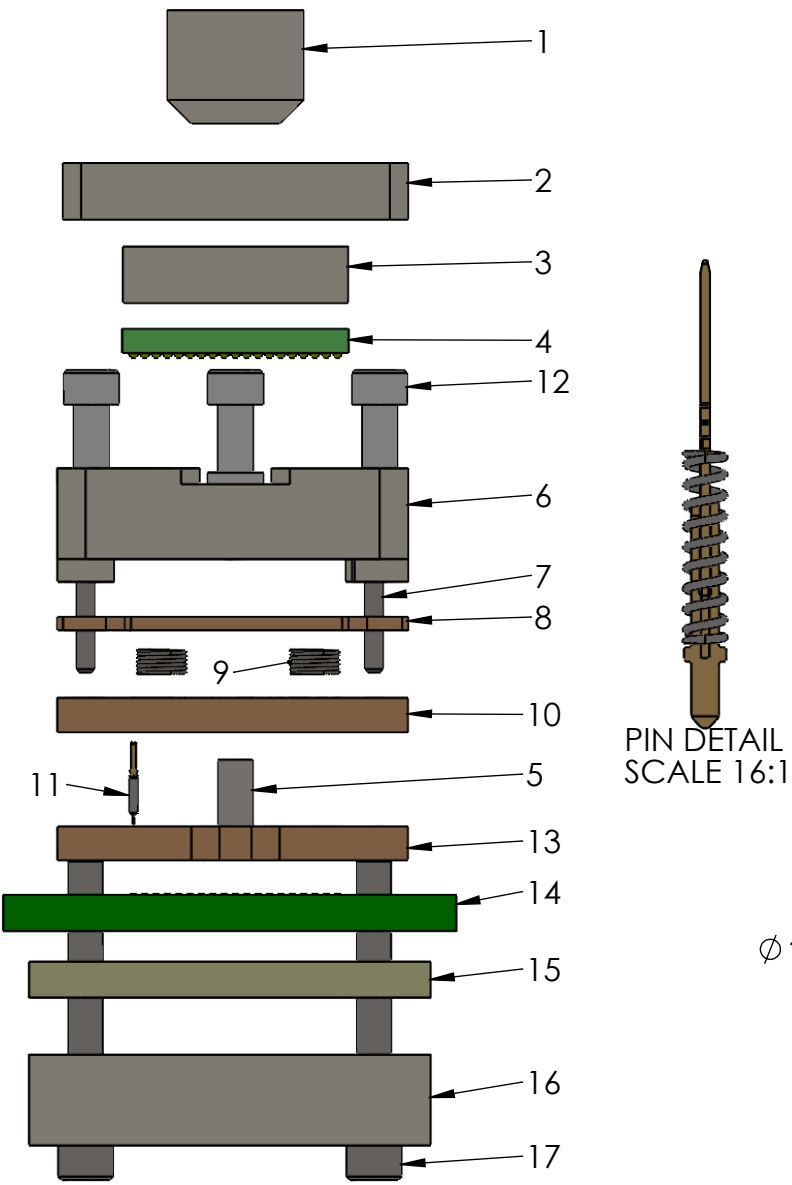
DIM	Minimum	Maximum
A		1.2
b		0.35
D	10.0 BSC	
E	10.0 BSC	

Description: BGA Spec

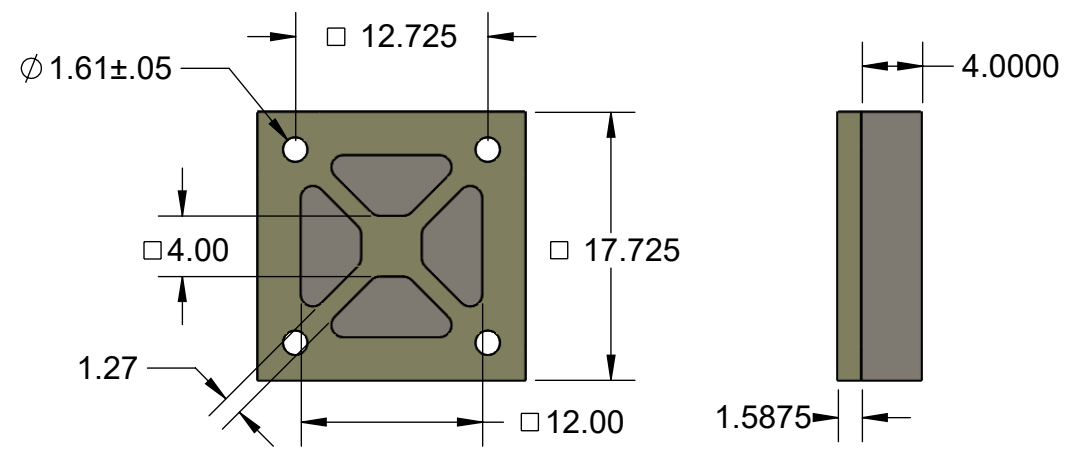
Primary dimension units are millimeters, Secondary dimension units are [inches]. Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-7004 Drawing		Material: Material <not specified> Finish: Weight: 10.88	STATUS: Released	SHEET: 3 OF 4	REV. A
 <div>Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</div>	DRAWN BY: B. Schatz		SCALE: 2:1		
	FILE: SBT-BGA-7004		DATE: 8/16/2013		




ITEM NO.	Description	Material
1	Compression Screw M6x1	Stainless Steel (18-8)
2	Socket Lid	7075-T6 Aluminum Alloy
3	Compression Plate	7075-T6 Aluminum Alloy
4	Test Chip	
5	#0-80, 90 deg., head pin guide screw, Peek material	PEEK unfilled
6	Socket Base SBT BGA 10x10	7075-T6 Alumium Alloy
7	Dowel pin, 1/32" X 1/4", SS	Stainless Steel (18-8)
8	Floating Guide SBT-BGA 10x10mm, 0.5mm pitch 19x19 array	Semitron MDS 100
9	Floating Guide Spring	Alloy Steel (SS)
10	SBT-BGA Middle Guide 10x10mm, 0.5mm pitch, 19x19 array	Semitron MDS 100
11	SBT Pin, SBT-BGA 0.5mm-0.8mm	
12	#0-80 Shoulder Screw, 1.59mm thread length	Stainless Steel (303)
13	SBT-BGA Bottom guide 10x10mm, 0.5mm Pitch, 19x19 array	Semitron MDS 100
14	Target PCB	
15	Insulation Plate	FR4 High temp
16	SBT/CBT Ni plt backing plate 13mm	7075-T6 Aluminum Alloy
17	#0-80 x 0.5, SH Cap Screw	Alloy Steel



Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches]. Weight is in grams.
Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-7004 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: Weight: 10.88	STATUS: Released	SHEET: 4 OF 4	REV. A
		DRAWN BY: B. Schatz	SCALE: 3:1	
		FILE: SBT-BGA-7004	DATE: 8/16/2013	